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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/781,557	02/18/2004	Patrick Perillat	02-GR2-463	9288	
23334 7590 07/01/2005			EXAM	EXAMINER	
•	i, GIBBONS, GUTMAN	POTTER, R	POTTER, ROY KARL		
& BIANCO P.L. ONE BOCA COMMERCE CENTER			ART UNIT	PAPER NUMBER	
	EST 77TH STREET, SUIT	2822			
BOCA RATON, FL 33487			DATE MAILED: 07/01/2005		

Please find below and/or attached an Office communication concerning this application or proceeding.

-		Application No.	Applicant(s)			
Office Action Summary		10/781,557	PERILLAT, PATRICK			
		Examiner	Art Unit			
		Roy K. Potter	2822			
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply						
A SHO THE I - Exter after - If the - If NO - Failu	ORTENED STATUTORY PERIOD FOR MAILING DATE OF THIS COMMUNICA asions of time may be available under the provisions of 3i SIX (6) MONTHS from the mailing date of this communic period for reply specified above is less than thirty (30) de period for reply is specified above, the maximum statuto re to reply within the set or extended period for reply will, eply received by the Office later than three months after the patent term adjustment. See 37 CFR 1.704(b).	TION. 7 CFR 1.136(a). In no event, however, may a ation. ays, a reply within the statutory minimum of the ry period will apply and will expire SIX (6) MO by statute, cause the application to become A	reply be timely filed  rty (30) days will be considered timely.  NTHS from the mailing date of this communication.  BANDONED (35 U.S.C. § 133).			
Status						
1)	Responsive to communication(s) filed o	n	•			
		☐ This action is non-final.				
3)□	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims						
<ul> <li>4)  Claim(s) 1-20 is/are pending in the application.</li> <li>4a) Of the above claim(s) is/are withdrawn from consideration.</li> <li>5)  Claim(s) is/are allowed.</li> <li>6)  Claim(s) 1-3,5-9 and 11 is/are rejected.</li> <li>7)  Claim(s) 4,10 and 12-20 is/are objected to.</li> <li>8)  Claim(s) are subject to restriction and/or election requirement.</li> </ul>						
Applicati	on Papers					
9) 🗆 .	The specification is objected to by the E	xaminer.				
10)☐ The drawing(s) filed on is/are: a)☐ accepted or b)☐ objected to by the Examiner.						
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).						
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).  11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.						
	inder 35 U.S.C. § 119					
12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).  a) All b) Some * c) None of:  1. Certified copies of the priority documents have been received.  2. Certified copies of the priority documents have been received in Application No  3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).  * See the attached detailed Office action for a list of the certified copies not received.						
Attachment(s)  1) Notice of References Cited (PTO-892)  4) Interview Summary (PTO-413)						
3) 🛛 Inform	Paper No(s)/Mail Date  Paper No(s)/Mail Date  Paper No(s)/Mail Date  Paper No(s)/Mail Date  Other:					

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# DETAILED ACTION

#### **DETAILED ACTION**

Claims 1 – 20 are pending.

### Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(a) the invention was known or used by others in this country, or patented or described in a printed publication in this or a foreign country, before the invention thereof by the applicant for a patent.

Claims 1-3, 5, 8-9 and 11 are rejected under 35 U.S.C. 102(a) as being anticipated by Pendse et al..

Pendse et al., U.S. Patent No. 6,828,220, discloses a flip-chip in leadframe package and process. As shown in Figure 1, the package 10 comprises a leadframe formed of spaced apart electrical connection leads. As shown, an integrated circuit chip 12 is attached to a front surface of the leads. Electrical connection means 14 connect the integrated circuit chip 12 to the leads. At least a portion of the leads are embedded into a block of encapsulation. As shown in the embodiment of Figure 3, part of the rear surface of the lead may be exposed.

#### Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claim 6 and 7 are rejected under 35 U.S.C. 103(a) as being unpatentable over Pendse et al. in view of Minamio et al..

The use of adhesive is not taught be Pendse et al. nor is the use of a wire to electrically connect the chip to the leads. However these are well known in the art.

Minamio et al., U.S. Patent No. 6208020, discloses a use of a die bonding adhesive 7, shown in Figure 16, to attach a chip 4 to a leadframe die pad 2. Also, the use of wire 5 to electrically connect the chip is shown.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to use adhesive and wire to connect the chip to the leadframe as Minamio et al. shows that these are used in resin molded semiconductor devices with a chip and a leadframe such as disclosed by Pendse et al.

## Allowable Subject Matter

Claims 4, 10, 12 - 20 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

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The prior art does not teach or suggest the recited rear recesses covered by encapsulation on the connection leads or the recited projection wall.

#### Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Roy K. Potter whose telephone number is 571 272 1842. The examiner can normally be reached on M-F.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Roy K Potter Primary Examiner Art Unit 2822